

ABSTRACT OF THE DISCLOSURE

An IC chip package is constructed to include a substrate, a chip, adhesive means, a cover, and a spacer. The substrate has a top side, a bottom side, and a plurality of conductive pads at the top side. The chip is fixedly mounted in the top side of the substrate, having a plurality of conductive pads respectively electrically connected to the conductive pads of substrate by respective bonding wires. The adhesive means is provided at the top side of the substrate around the border area. The spacer is connected between the substrate and the cover to keep the cover from the substrate at a distance. The spacer has at least two columns fixedly connected between the substrate and the cover.